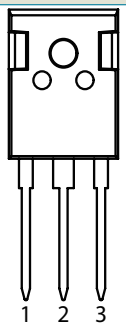
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I_{GT}	gate trigger current	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C; Fig. 7; Fig. 8		-	-	70	mA
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	V_{DM} = 804 V; T_j = 125 °C; R_{GK} = 100 Ω; (V_{DM} = 67% of V_{DRM}); exponential waveform		1500	-	-	V/µs
		V_{DM} = 804 V; T_j = 150 °C; R_{GK} = 100 Ω; (V_{DM} = 67% of V_{DRM}); exponential waveform		1000	-	-	V/µs

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		 sym037
2	A	anode		
3	G	gate		
mb	A	mounting base; connected to anode		

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BT158W-1200T	TO247	BT158W-1200TQ	Tube	30	TO247N	20-July-2016

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage			-	1200	V
V_{RRM}	repetitive peak reverse voltage			-	1200	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq 117$ °C		-	80	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 117$ °C; Fig 1; Fig 2; Fig 3		-	126	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(init)} = 25$ °C; $t_p = 10$ ms; Fig 4; Fig 5		-	1100	A
		half sine wave; $T_{j(init)} = 25$ °C; $t_p = 8.3$ ms		-	1210	A
I^2t	I^2t for fusing	$t_p = 10$ ms; sine-wave pulse; $T_{j(init)} = 25$ °C; no voltage reapplied		-	6115	A^2s
dI_T/dt	rate of rise of on-state current	$I_G = 200$mA		-	150	A/µs
I_{GM}	peak gate current			-	8	A
V_{RGM}	peak reverse gate voltage			-	5	V
P_{GM}	peak gate power			-	20	W
$P_{G(AV)}$	average gate power	over any 20 ms period		-	1	W
T_{stg}	storage temperature			-40	150	°C
T_j	junction temperature			-	150	°C

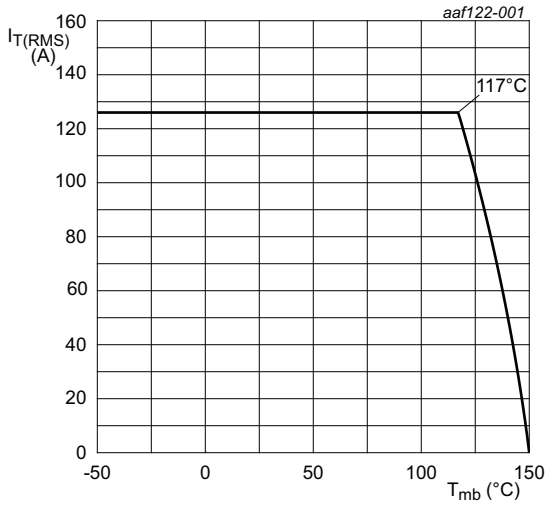
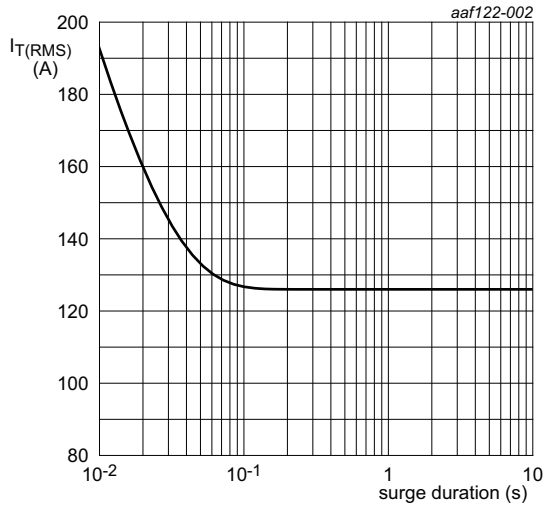
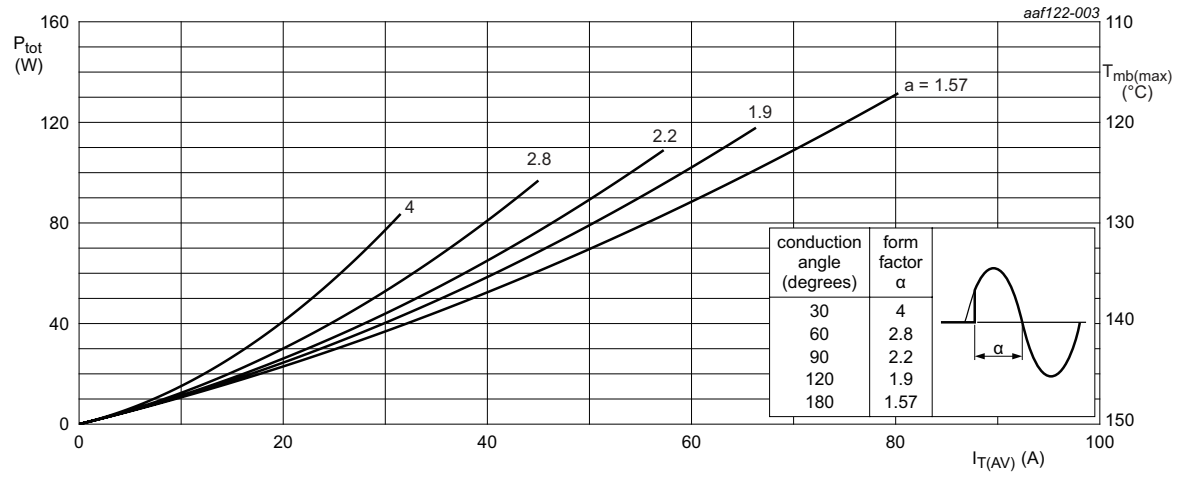


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values



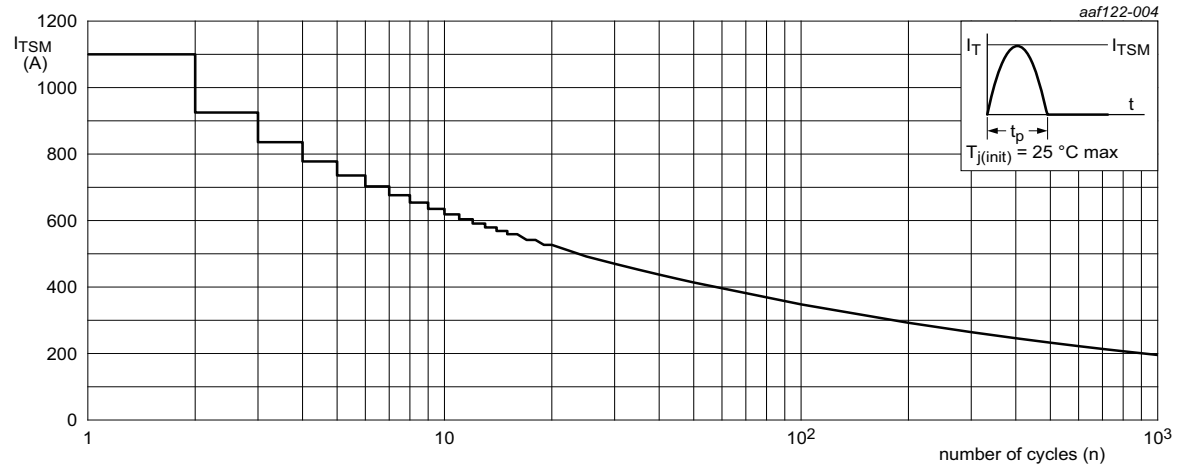
f = 50 Hz; $T_{mb} = 117$ °C

Fig. 2. RMS on-state current as a function of surge duration; maximum values



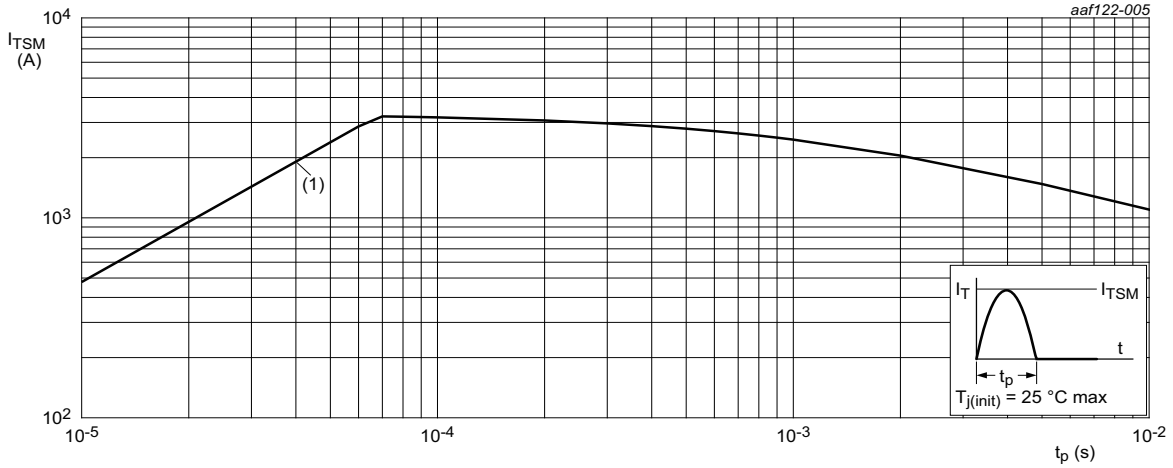
α = conduction angle
a = form factor = $I_{T(RMS)}$ / $I_{T(AV)}$

Fig. 3. Total power dissipation as a function of average on-state current; maximum values



f = 50 Hz

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



$t_p \leq 10$ ms
(1) dI_T/dt limit

Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values

8. Thermal & Mechanical characteristics

Table 5. Thermal & Mechanical characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	full cycle; Fig 6		-	-	0.25	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	50	-	K/W

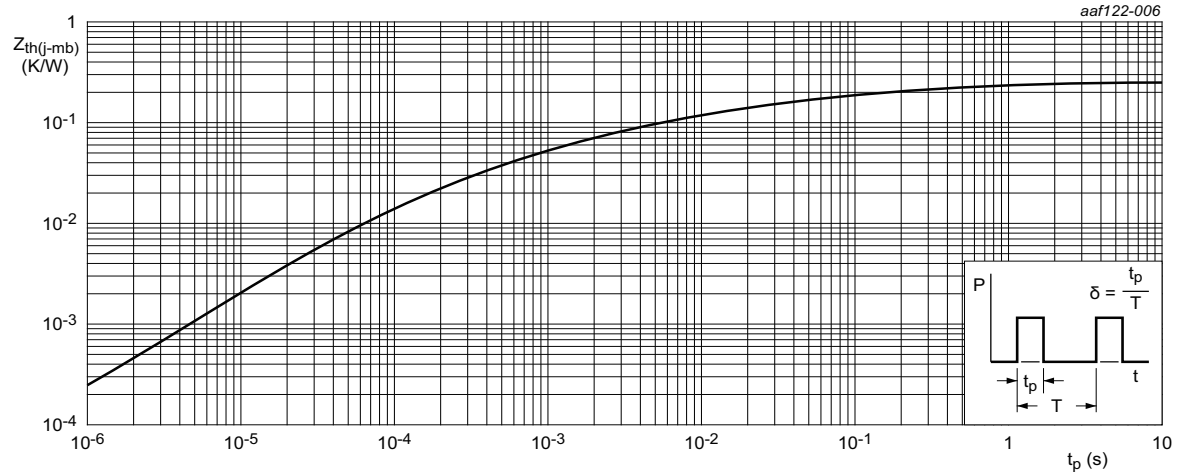


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I_{GT}	gate trigger current	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C; Fig. 7; Fig. 8		-	-	70	mA
I_L	latching current	V_D = 12 V; I_G = 0.1 A; T_j = 25 °C; Fig. 9		-	-	300	mA
I_H	holding current	V_D = 12 V; T_j = 25 °C; Fig. 10		-	-	200	mA
V_T	on-state voltage	I_T = 80 A; T_j = 25 °C; Fig. 11		-	-	1.35	V
		I_T = 160 A; T_j = 25 °C; Fig. 11		-	-	1.65	V
V_{GT}	gate trigger voltage	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C; Fig. 12		-	0.7	1	V
		V_D = 800 V; I_T = 0.1 A; T_j = 125 °C		0.25	0.4	-	V
I_D	off-state current	V_D = 1200 V; T_j = 25 °C		-	-	10	µA
		V_D = 1200 V; T_j = 125 °C		-	-	5	mA
I_R	reverse current	V_D = 1200 V; T_j = 25 °C		-	-	10	µA
		V_D = 1200 V; T_j = 125 °C		-	-	5	mA
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	V_{DM} = 804 V; T_j = 125 °C; R_{GK} = 100 Ω; (V_{DM} = 67% of V_{DRM}); exponential waveform		1500	-	-	V/µs
		V_{DM} = 804 V; T_j = 150 °C; R_{GK} = 100 Ω; (V_{DM} = 67% of V_{DRM}); exponential waveform		1000	-	-	V/µs
t_{gt}	gate-controlled turn-on time	I_{TM} = 40 A; V_D = 800 V; I_G = 0.1 A; dI_G/dt = 5 A/µs; T_j = 25 °C		-	2	-	µs
t_q	commutated turn-off time	V_{DM} = 804 V; T_j = 125 °C; I_{TM} = 20 A; V_R = 25 V; $(dI_T/dt)_M$ = 30 A/µs; dV_D/dt = 50 V/µs; $R_{GK(ext)}$ = 100 kΩ; (V_{DM} = 67% of V_{DRM})		-	150	-	µs

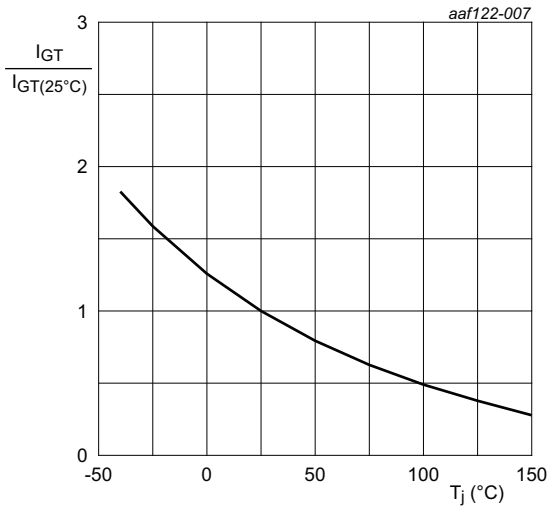


Fig. 7. Normalized gate trigger current as a function of junction temperature

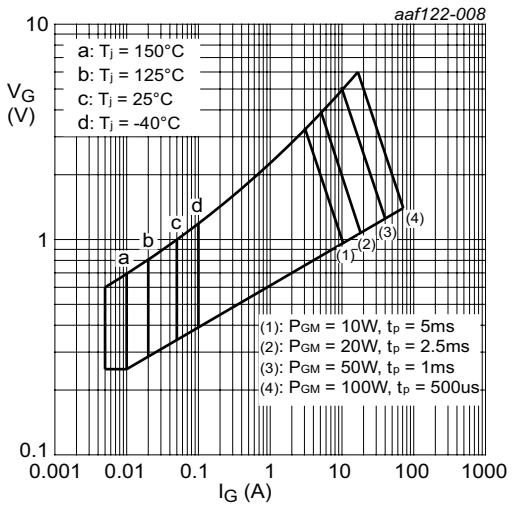


Fig. 8. Gate voltage as a function of gate current

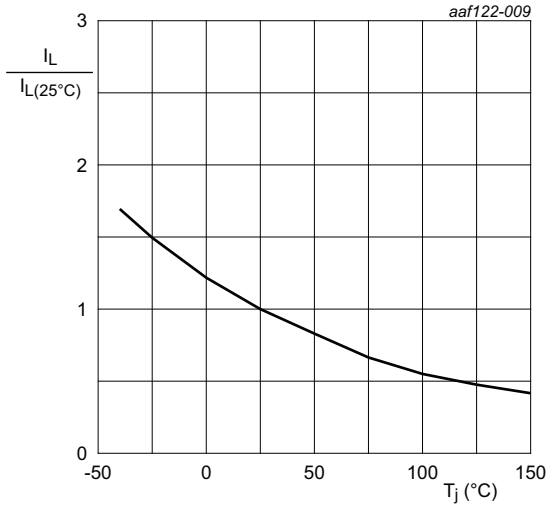


Fig. 9. Normalized latching current as a function of junction temperature

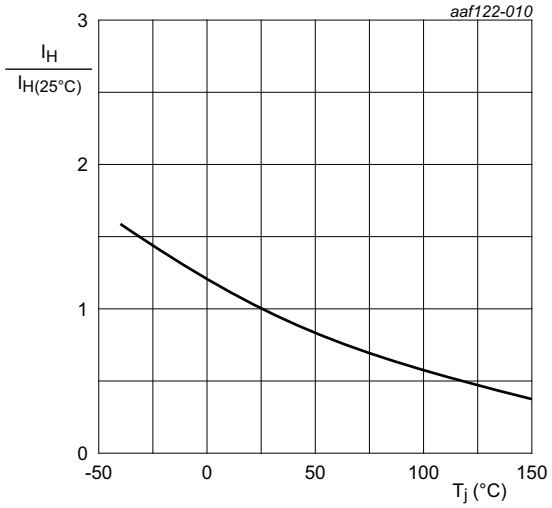
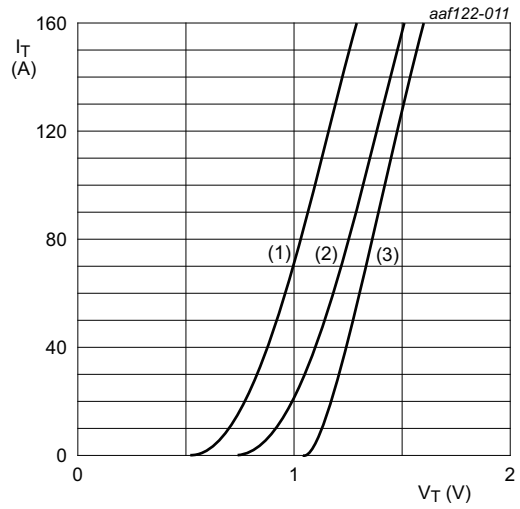


Fig. 10. Normalized holding current as a function of junction temperature



V_o = 0.984 V; R_s = 0.0033 Ω
(1) T_j = 150 °C; typical values
(2) T_j = 150 °C; maximum values
(3) T_j = 25 °C; maximum values

Fig. 11. On-state current as a function of on-state voltage

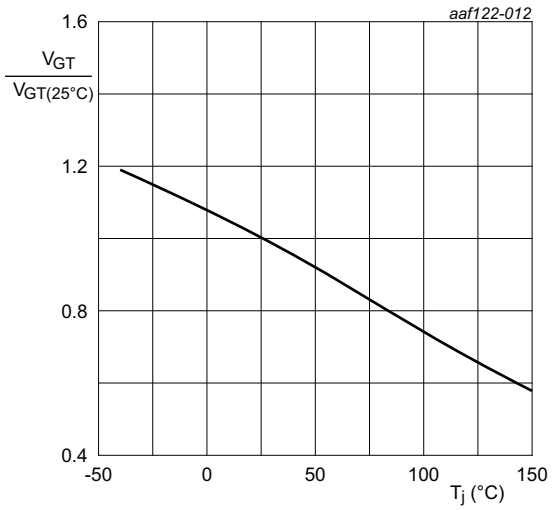
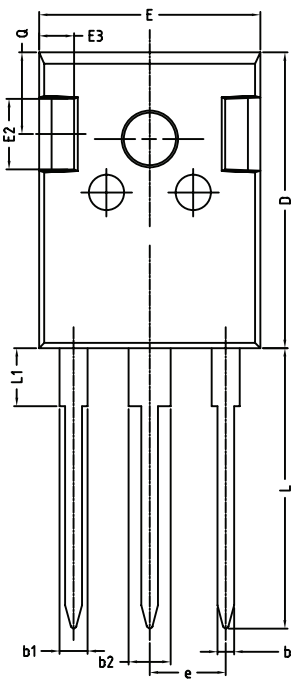


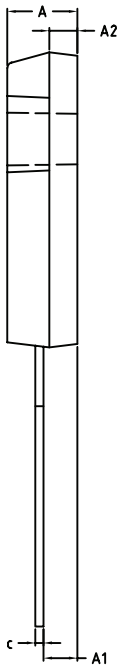
Fig. 12. Normalized gate trigger voltage as a function of junction temperature

10. Package outline

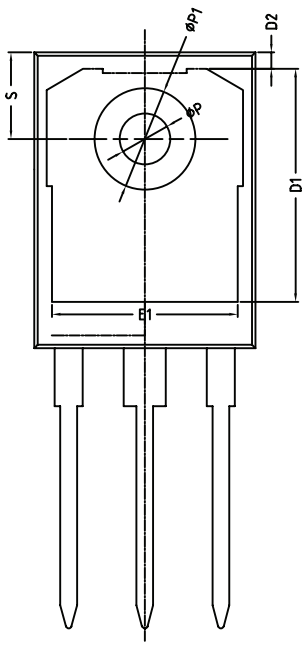
Plastic single-ended through-hole package; heatsink mounted; 1 mounting hole; 3-lead TO-247 SOT429N



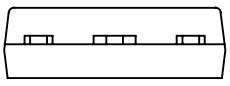
TOP VIEW



SIDE VIEW



BOTTOM VIEW



SIDE VIEW

UNIT		A	A1	A2	b	b1	b2	c	D	D1	D2	E	E1	E2	E3	e	L	L1	P	P1	Q	S
mm	MAX	5.20	2.60	2.10	1.40	2.20	3.20	0.70	21.10	16.85	1.35	15.90	13.50	5.20	2.60	5.45	20.10	4.75	3.70	7.40	6.00	6.25
	NOM																					
	MIN	4.70	2.20	1.90	1.00	1.80	2.80	0.50	20.90	16.25	1.05	15.70	13.10	4.80	2.40		19.80	–	3.50	–	5.60	6.05

OUTLINE VERSION	REFERENCES				PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT429N		TO-247				

11. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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12. Contents

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Date of release: 26 April 2020